

**FROM IDEAS TO  
NEXT GENERATION  
SMART SYSTEMS**

4-7 JULY 2023, VILLACH, AUSTRIA

**EPoSS – European Association on Smart Systems Integration** – will hold its Annual Forum 2023 on July 4–7 in Villach, Austria. This year’s event will be hosted by the EPoSS member and strategic partners **Silicon Austria Labs** and **Silicon Alps**.

In order to present the latest developments in Smart Systems Integration (SSI), we invite you to send your abstracts for presentations and **showcase your latest Smart Systems innovations or technology developments** for Smart Systems Integration. Presentation could include one or more of the following topic areas:

**Smart Systems Integration research & developments for the following applications:**

Next Generation of Smart Systems incl. Sensors and Actuators for e.g.

- Smart and Sustainable Mobility
- Internet of Everything Applications
- Green ECS for decarbonisation
- Digitisation and Robotics
- Energy Solutions
- Smart Health
- Connectivity

**Latest developments and innovative technologies for Smart Systems Integration in the area of**

New Innovative Technologies e.g.

- New Manufacturing Technologies, Additive Manufacturing and 3D Printed Electronics
- Advanced and sustainable Packaging Technologies
- Photonics Integration
- Large Scale Technologies and Flexible and Wearable Electronics
- Artificial Intelligence at the Edge
- Quantum Sensing
- Design Methodologies, Security, Safety, Reliability and Resilience

Brokerage opportunities will be organised to network with especially SMEs, start-ups and young researchers.

If you wish to participate in the Call for Presentations, please submit your abstract (**1,500–3,000 characters**) together with your full contact details as well as a short biography to <https://ssl.vdivde-it.de/formular/eposs> by **April 12, 2023**.

Please use the **template** for abstract submission, which can be found at: <https://www.smart-systems-integration.org/event/eposs-annual-forum-2023>

**Presentations will be selected by the EPoSS Annual Forum 2023 Technical Committee.**

Invitations for the authors of selected presentations will be sent out until **May 2, 2023**.